



MODEL 6400

AUTOMATIC HIGH ACCURACY DIE ATTACH SYSTEM

Performs **MCM, Hybrid, Flip Chip, Eutectic, Silver Glass** die attach applications.

Versatile and **User Friendly** machine based on a PC platform running under Windows XP®.

Fully automatic system designed for highest flexibility and easy operation.

Very High Accuracy closed loop servo systems control the X, Y motion of the bonding head.

High resolution **Digital Vision** and **Image Processing** system.

Adhesive is applied in single/multi dot and shape patterns by the **Volumetric Dispenser**. Library of complex pre-taught dispense shapes.

Stamping (Pin Transfer) 75 µm and under adhesive dots.

Unique one-pass, wet **Die Stacking** capability with **BLT control** of all dice.

Die Presentation:

- Up to 30 Waffle/Gel packs.
- Up to 8 Tape & Reel feeders.
- 300 mm Wafers.

Specializing in unusual **Die Sizes** and **Aspect Ratios**. Capability to attach **CCD, Sensors** and other sensitive components.

Capability to handle **MEMS** devices. Experience with picking MEMS from wafer, design of special pickup tools, accurate BLT control for sealing.

Full **Flip Chip** process including chip flipping, bump fluxing and chip final alignment over Up Looking Camera.

Heated substrates with gas cover and **heated pickup tools** available for **Eutectic** processes.

Ultrasonic bond head available for **Eutectic** and Gold to Gold Interconnection.

Specification Highlights

Work Area: up to 10" x 12".

Die size range: 0.008" to over 1".

Die Material: GaAs, Si, Glass, Metal, etc.

Pickup/Bond Force: 40 to 4,000 grams.

Accuracy: 3µm @ 3σ - application dependent.

Throughput: up to 1000 CPH.